LNJ312G83RA

Hight Bright Surface Mounting Chip LED

TSS Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit				
Power dissipation	P _D	55	mW				
Forward current	I _F	20	mA				
Pulse forward current *	I _{FP}	60	mA				
Reverse voltage	V _R	4	V				
Operating ambient temperature	T _{opr}	-30 to +85	°C				
Storage temperature	T _{stg}	-40 to +100	°C				

Lighting Color

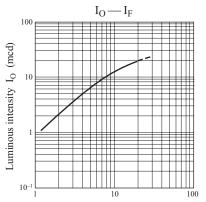
• Green

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

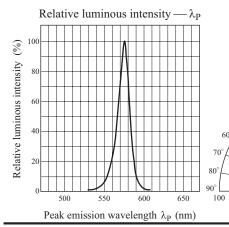
Electro-Optical Characteristics $T_a = 25^{\circ}C$

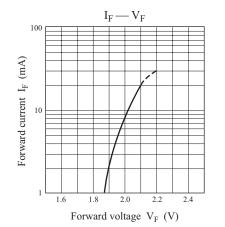
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_{\rm F} = 10 {\rm mA}$	6.4	12.0		mcd
Reverse current	I _R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_{\rm F} = 10 \text{ mA}$		2.03	2.5	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 \text{ mA}$		575		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		15		nm

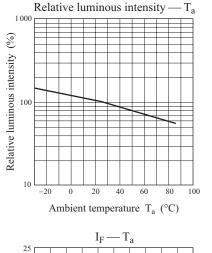
Note) *: Measurement tolerance: ±20%



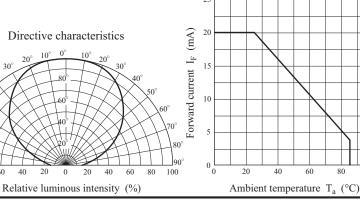
Forward current I_F (mA)







 $-T_a$



0 20

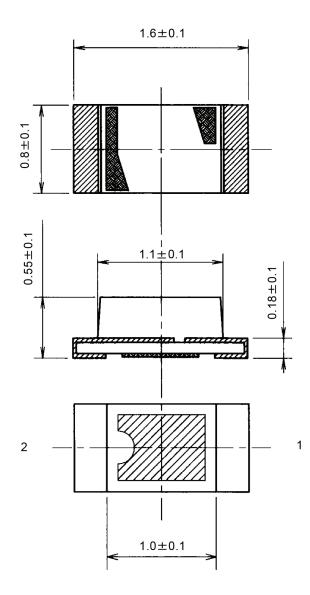
0

50

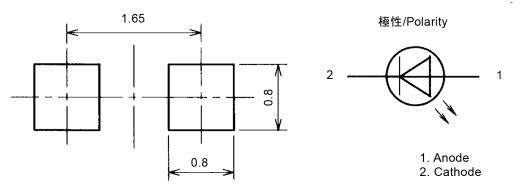
80

60 40 100

Package (Unit: mm)



推奨パターン/Recommended Land Layout



(注 1) パッケージ寸法については電極バリを含まない。(Note1) Electrode projection is not included in the package dimensions.

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No.020210